

POLISHING APPARATUS AND POLISHING METHOD

ABSTRACT

A film thickness measuring apparatus and an end point detector monitor a film thickness of a conductive film based on an output of an eddy current sensor disposed in a polishing table. The output of the eddy current sensor includes an impedance component, and when a resistance component and a reactance component of the impedance component are associated with the respective axes of a coordinate system having two orthogonal coordinate axes, at least some points on the coordinate system corresponding to the impedance component form at least a part of a circle. The film thickness measuring apparatus determines a distance between a point on the coordinate system and the center of the circle, determines the film thickness from the impedance component and corrects the determined film thickness using the determined distance.

Representative drawing: Fig. 2